# MBRD5Hbt00HAG

# SWITCHMODE <sup>™</sup> Schottky Power Rectifier Surface Mount Power Package

This series of Power Rectifiers employs the Schottky Barrier principle in a large metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use in low voltage, high frequency switching power supplies, free wheeling diodes, and polarity protection diodes.

### Features

- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured Not Sheared!
- This is a Pb-Free Device

## Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 0.4 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V) Human Body Model, 3B (>8000 V)

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100	V
Average Rectified Forward Current (Rated $V_R$ ) $T_C$ = 146°C	I <sub>F(AV)</sub>	5	A
Peak Repetitive Forward Current (Rated V <sub>R</sub> , Square Wave, 20 kHz) $T_{C}$ = 146°C	I <sub>FRM</sub>	10	A
onrepetitive Peak Surge Current I <sub>FSM</sub> 105 Surge applied at rated load conditions alfwave, single phase, 60 Hz)		A	
Operating Junction and Storage Temperature Range (Note 1)	T <sub>J</sub> , T <sub>stg</sub>	-65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

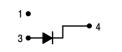
1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .



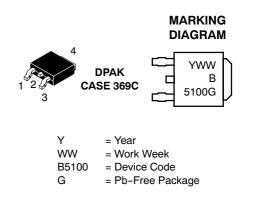
## **ON Semiconductor®**

http://onsemi.com

## SCHOTTKY BARRIER RECTIFIER 5 AMPERES, 100 VOLTS



(Pin 1: No Connect)



#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# 查爾MABREAGTERISTICS应商

Characteristic	Symbol	Value	Unit
Thermal Resistance, – Junction-to-Case (Note 2) – Junction-to-Ambient (Note 2)	R <sub>θJC</sub> R <sub>θJA</sub>	1.6 95.8	°C/W

2. When mounted using minimum recommended pad size on FR-4 board.

#### ELECTRICAL CHARACTERISTICS

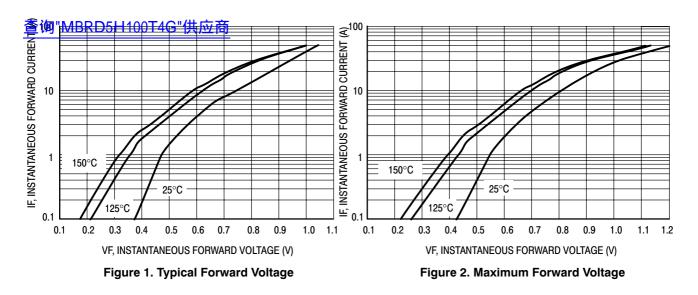
Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) (I <sub>F</sub> = 5 A, T <sub>J</sub> = 25°C) (I <sub>F</sub> = 5 A, T <sub>J</sub> = 125°C)	V <sub>F</sub>	0.71 0.60	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 125^{\circ}C$ ) (Rated dc Voltage, $T_J = 25^{\circ}C$ )	I <sub>R</sub>	4.5 3.5	mA μA

3. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRD5H100T4G	DPAK (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



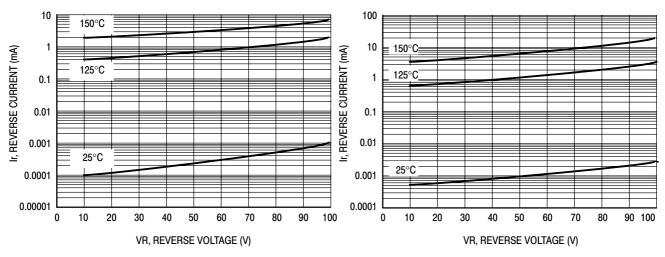
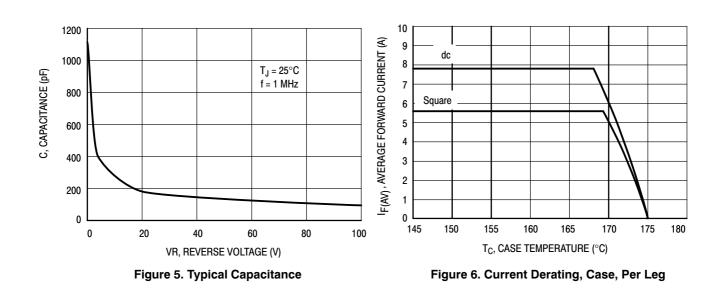




Figure 4. Maximum Reverse Current



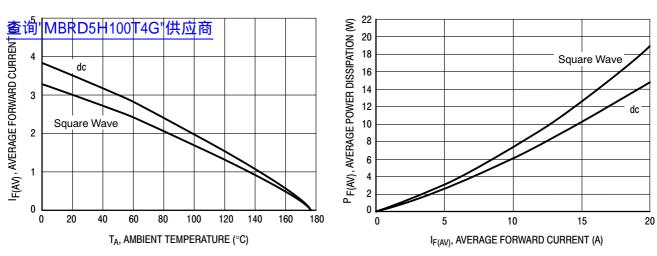


Figure 7. Current Derating, Ambient, Per Leg

Figure 8. Forward Power Dissipation

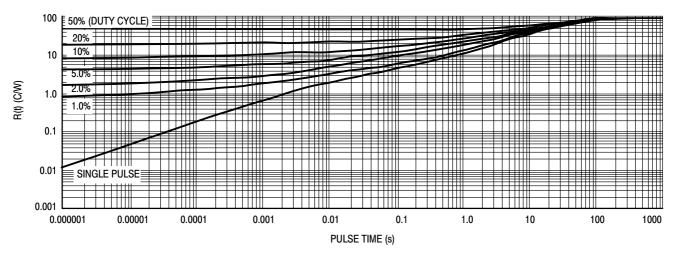
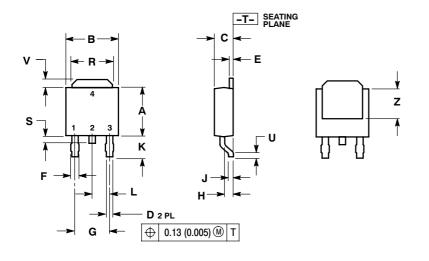


Figure 9. Thermal Response, Junction-to-Case

### 查询"MBRD5H100T4G"供应商

#### PACKAGE DIMENSIONS

**DPAK (SINGLE GUAGE)** CASE 369C ISSUE O

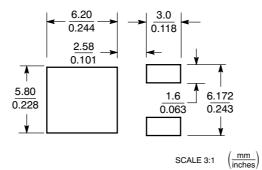


NOTES:

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58 BSC	
н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
κ	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
V	0.035	0.050	0.89	1.27
Z	0.155		3.93	

SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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